

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-6 (canceled)

7 (currently amended). A process for producing a transponder or smart card body comprising forming a component layer comprising at least one ~~one or more~~ electronic ~~circuits or transponders~~ circuit or transponder using a thermoplastic hot-melt adhesive, wherein the hot-melt adhesive has a processing viscosity ranging from 100 mPa·s to 100,000 mPa·s and at least partially encapsulates the electronic circuits or transponders.

8 (previously presented). The process of claim 7 wherein the forming of the component layer is carried out in an injection molding process at an injection molding pressure ranging from 1 bar to 50 bar and an injection molding temperature from 80 °C to 250 °C.

9 (previously presented). The process of claim 8 wherein the injection molding temperature ranges from 100 °C to 230 °C.

10 (previously presented). The process of claim 9 wherein the injection molding pressure ranges from 10 to 30 bar.

11 (previously presented). The process of claim 8 wherein the forming comprises providing an electronic circuit on a support film and injecting the hot-melt adhesive onto the electronic circuit in an injection mold.

12 (previously presented). The process of claim 8 wherein the forming comprises applying a film of the hot-melt adhesive in an injection mold, placing the electronic

component on the film, and injecting a second amount of the hot-melt adhesive onto the electronic component to encapsulate the electronic component in the hot-melt adhesive.

13 (previously presented) The process of claim 8 wherein the hot-melt adhesive comprises a polyamide, polyurethane, polyester, atactic polypropylene, ethylene-vinyl acetate copolymers, or low molecular mass polyethylene copolymers, or combinations thereof.

14 (previously presented) A transponder or card body produced by the process of claim 8.

15 (previously presented). The transponder or card body of claim 14 wherein the card body is a smart card.

16 (previously presented). The process of claim 7, wherein the hot-melt adhesive comprises a polyamide, polyurethane, polyester, atactic polypropylene, ethylene-vinyl acetate copolymers, or low molecular mass polyethylene copolymers, or combinations thereof.

17 (previously presented). A transponder or card body produced by the process of claim 7.

18 (previously presented) The transponder or card body of claim 17 wherein the card body is a smart card.